

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kuo-Hsien Liao	08/03/2011
Chi-Hong Chan	08/03/2011
Fuyu Shih	08/02/2011
RECEIVING PARTY DATA	
Name:	Advanced Semiconductor Engineering, Inc.
Street Address:	No. 26, Chin 3rd Road, Nantze Export Processing Zone
City:	Kaohsiung
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13205558
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	George D. Morgan
Total Attachments: 2 source=ASE2390Assignment#page1.tif source=ASE2390Assignment#page2.tif	

OP \$40.00 13205558

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PATENT
REEL: 026728 FRAME: 0053

ASSIGNMENT OF APPLICATION

WHEREAS, We,

Liao, Kuo-Hsien, of No. 420, Fengshu W. St., Nantun Dist., Taichung City 40846, Taiwan (R.O.C.) and a citizen of Taiwan R.O.C;

Chan, Chi-Hong, of Flat B, G/F, 21 Fa Po Street, Kowloon, H.K. and a citizen of Canada; and

Shih Fuyu, of Cumbredel Sol 45A B-03726 Benitachell Alicante, Spain and a citizen of Belgium

("Assignors"), have an interest in the invention entitled "**SEMICONDUCTOR PACKAGE INTEGRATED WITH CONFORMAL SHIELD AND ANTENNA**" which is the subject of a United States application for patent entitled above and in a Taiwan patent application filed on September 9, 2010, with serial number 99130565 and a U.S. provisional application filed on January 7, 2011 with serial number 61/430,808; and

WHEREAS, **Advanced Semiconductor Engineering, Inc.**, a corporation organized and existing under and by virtue of the laws of Taiwan R.O.C. with an address at No. 26, Chin 3rd Road, Nantze Export Processing Zone, Kaohsiung, Taiwan R.O.C. ("Assignee"), is desirous of acquiring Assignor's interest in the invention;

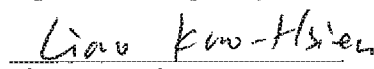
NOW THEREFORE, Assignor acknowledges receipt and adequacy of good and valuable consideration in exchange for this Assignment, and assigns to Assignee and its successors in interest, the full and exclusive right, title and interest to the invention described in the patent application listed above, in the United States of America and all foreign countries, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, for the full term of the patent, including extensions of time, the same as if held by Assignor had this Assignment not been made.

Assignor covenants and agrees to cooperate with Assignee and execute all instruments or documents requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to the following: non-provisional utility, provisional, continuation, continuation-in-part, divisional, renewal or substitute, reissue, re-examination, or extension.

Assignor covenants and agrees to cooperate with Assignee in any litigation regarding the invention, patents or applications regarding the invention, including testifying for the benefit of Assignee.

Assignor covenants that no assignment, sale or agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

Signed and Accepted by:


Liao, Kuo-Hsien

2011-8-3
Date


Chan, Chi-Hong

2011-8-3
Date

Shih Fuyu

Date

ASSIGNMENT OF APPLICATION

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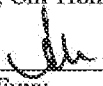
Signed and Accepted by:

Liao, Kuo-Hsien

Date

Chan, Chi-Hong

Date



Shih Fuyu

Date

August 2nd 2011